

Recent Research in 3-D Circuit Design and Related Test Circuits

Prof. Eby G. Friedman, University of Rochester, NY, USA

The focus of this presentation will be on 3-D design methodologies and related test circuits. A methodology for distributing on-chip power regulators across multiple planes within a 3-D system will be discussed. This topic will be followed by a discussion of several 3-D test circuits, and related TSV interconnect modeling and design algorithms.